Renesas Electronics America Inc - R7FS5D97E3A01CFP#AA0 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, MMC/SD, QSPI, SCI, SPI, SSI, UART/USART, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	76
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	64K x 8
RAM Size	640K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 19x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r7fs5d97e3a01cfp-aa0

Table 1.16 Pin functions (3 of 5)

Function	Signal	I/O	Description
SPI	RSPCKA, RSPCKB	I/O	Clock input/output pin.
	MOSIA, MOSIB	I/O	Input or output pins for data output from the master.
	MISOA, MISOB	I/O	Input or output pins for data output from the slave.
	SSLA0, SSLB0	I/O	Input or output pin for slave selection.
	SSLA1 to SSLA3, SSLB1 to SSLB3	Output	Output pins for slave selection.
QSPI	QSPCLK	Output	QSPI clock output pin.
	QSSL	Output	QSPI slave output pin.
	QIO0 to QIO3	I/O	Data0 to Data3.
CAN	CRX0, CRX1	Input	Receive data.
	CTX0, CTX1	Output	Transmit data.
USBFS	VCC_USB	Input	Power supply pins.
	VSS_USB	Input	Ground pins.
	USB_DP	I/O	D+ I/O pin of the USB on-chip transceiver. Connect this pin to the D+ pin of the USB bus.
	USB_DM	I/O	D- I/O pin of the USB on-chip transceiver. Connect this pin to the D- pin of the USB bus.
	USB_VBUS	Input	USB cable connection monitor pin. Connect this pin to VBUS of the USB bus. The VBUS pin status (connected or disconnected) can be detected when the USB module is operating as a function controller.
	USB_EXICEN	Output	Low-power control signal for external power supply (OTG) chip.
	USB_VBUSEN	Output	VBUS (5 V) supply enable signal for external power supply chip.
	USB_OVRCURA, USB_OVRCURB	Input	Connect the external overcurrent detection signals to these pins. Connect the VBUS comparator signals to these pins when the OTG power supply chip is connected.
	USB_ID	Input	Connect the MicroAB connector ID input signal to this pin during operation in OTG mode.
USBHS	VCC_USBHS	Input	Power supply pin.
	VSS1_USBHS	Input	Ground pin.
	VSS2_USBHS	Input	Ground pin.
	AVCC_USBHS	Input	Analog power supply pin for the USBHS.
	AVSS_USBHS	Input	Analog ground pin for the USBHS. Must be shorted to the PVSS_USBHS pin.
	PVSS_USBHS	Input	PLL circuit ground pin for the USBHS. Must be shorted to the AVSS_USBHS pin.
	USBHS_RREF	I/O	USBHS reference current source pin. Connect this pin to the AVSS_USBHS pin through a 2.2-kΩ resistor (±1%).
	USBHS_DP	I/O	USB bus D+ data pin.
	USBHS_DM	I/O	USB bus D- data pin.
	USBHS_EXICEN	Output	Connect this pin to the OTG power supply IC.
	USBHS_ID	Input	Connect this pin to the OTG power supply IC.
	USBHS_VBUSEN	Output	VBUS power enable signal for USB.
	USBHS_OVRCURA, USBHS_OVRCURB	Input	Overcurrent pin for USB.
	USBHS_VBUS	Input	USB cable connection monitor input pin.

Pin number					Power, System, Clock, Debug, CAC	Interrupt	I/O port	Extbus		Timers				Communication interfaces										Analog		HMI	
BGA176	LQFP176	LGA145	LQFP144	LQFP100				External bus	SDRAM	AGT	GPT	GPT	RTC	USBFS, CAN	SCI0,2,4,6,8 (30 MHz)	SCI1,3,5,7,9 (30 MHz)	IIC	SPI, QSPI	SSIE	ETHERC (MII) (25 MHz)	ETHERC (RMII) (50 MHz)	USBHS	SDHI	ADC12	DAC12, ACMPHS	CTSU	GLCDC, PDC
-	-	G10	22	-	-	-	P713	-	-	AGTOA0	-	GTIOC2A	-	-	-	-	-	-	-	-	-	-	-	-	-	TS17	-
-	-	F11	23	-	-	-	P712	-	-	AGTOB0	-	GTIOC2B	-	-	-	-	-	-	-	-	-	-	-	-	-	TS16	-
-	-	E13	24	-	-	-	P711	-	-	AGTEE0	-	-	-	-	-	CTS1_RTS1/SS1	-	-	-	ET0_TX_CLK	-	-	-	-	-	TS15	-
-	-	E12	25	-	-	-	P710	-	-	-	-	-	-	-	-	SCK1	-	-	-	ET0_TX_ER	-	-	-	-	-	TS14	-
-	-	F10	26	-	-	IRQ10	P709	-	-	-	-	-	-	-	-	TXD1/MOSI1/SDA1	-	-	-	ET0_ETXD2	-	-	-	-	-	TS13	-
-	-	D13	27	16	CACREF	IRQ11	P708	-	-	-	-	-	-	-	-	RXD1/MISO1/SCL1	-	SSLA3_B	AUDIO_CLK	ET0_ETXD3	-	-	-	-	-	TS12	PCKO
E14	36	E11	28	17	-	IRQ8	P415	-	-	-	-	GTIOC0A	-	USB_VBUSEN	-	-	-	SSLA2_B	-	ET0_TX_EN	RMII0_TXD_EN_A	-	SD0CD_A	-	-	TS11	PIXD5
D15	37	D12	29	18	-	IRQ9	P414	-	-	-	-	GTIOC0B	-	-	-	-	-	SSLA1_B	-	ET0_RX_ER	RMII0_TXD1_A	-	SD0WP_A	-	-	TS10	PIXD4
E13	38	E10	30	19	-	-	P413	-	-	-	GTOUUP	-	-	-	CTS0_RTS0/SS0	-	-	SSLA0_B	-	ET0_ETXD1	RMII0_TXD0_A	-	SD0CLK_A	-	-	TS09	PIXD3
D14	39	C13	31	20	-	-	P412	-	-	AGTEE1	GTOULO	-	-	-	SCK0	-	-	RSPCKA_B	-	ET0_ETXD0	REF50CK0_A	-	SD0CMD_A	-	-	TS08	PIX02
C15	40	D11	32	21	-	IRQ4	P411	-	-	AGTOA1	GTOVUP	GTIOC9A	-	-	TXD0/MOSI0/SDA0	CTS3_RTS3/SS3	-	MOSIA_B	-	ET0_ERXD1	RMII0_RXD0_A	-	SD0DAT0_A	-	-	TS07	PIX01
C14	41	C12	33	22	-	IRQ5	P410	-	-	AGTOB1	GTOVLO	GTIOC9B	-	-	RXD0/MISO0/SCL0	SCK3	-	MISOA_B	-	ET0_ERXD0	RMII0_RXD1_A	-	SD0DAT1_A	-	-	TS06	PIXD0
B15	42	B13	34	23	-	IRQ6	P409	-	-	-	GTOWUP	GTIOC10A	-	USB_EXICEN	-	TXD3/MOSI3/SDA3	-	-	-	ET0_RX_CLK	RMII0_RX_ER_A	USBHS_EXICEN	-	-	-	TS05	HSYNC
D13	43	D10	35	24	-	IRQ7	P408	-	-	-	GTOWLO	GTIOC10B	-	USB_ID	-	RXD3/MISO3/SCL3	SCL0_B	-	-	ET0_CRS	RMII0_CRS_DV_A	USBHS_ID	-	-	-	TS04	PIXCLK
A15	44	A13	36	25	-	-	P407	-	-	AGTIO0	-	-	RTCOUT	USB_VBUS	CTS4_RTS4/SS4	-	SDA0_B	SSLB3_A	-	ET0_EXOUT	ET0_EXOUT	-	-	ADTRG0	-	TS03	-
C13	45	B11	37	26	VSS_USB	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
B14	46	A12	38	27	-	-	-	-	-	-	-	-	-	USB_DM	-	-	-	-	-	-	-	-	-	-	-	-	-
A14	47	B12	39	28	-	-	-	-	-	-	-	-	-	USB_DP	-	-	-	-	-	-	-	-	-	-	-	-	-
B13	48	A11	40	29	VCC_USB	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
C12	49	C11	41	30	-	-	P207	A17	-	-	-	-	-	-	-	-	-	SSLB2_A/QSSL	-	-	-	-	-	-	-	TS02	LCD_DATA23_B
D12	50	B10	42	31	-	IRQ0-DS	P206	WAIT	-	-	GTIU	-	-	USB_VBUSEN	RXD4/MISO4/SCL4	-	SDA1_A	SSLB1_A	SSIDATA1_A	ET0_LINKSTA	ET0_LINKSTA	-	SD0DAT2_A	-	-	TS01	-
E12	51	A10	43	32	CLKOUT	IRQ1-DS	P205	A16	-	AGTO1	GTIV	GTIOC4A	-	USB_OVRCURA-DS	TXD4/MOSI4/SDA4	CTS9_RTS9/SS9	SCL1_A	SSLB0_A	SSILRCK1/SSIFS1_A	ET0_WOL	ET0_WOL	-	SD0DAT3_A	-	-	TSCAP	-
A13	52	C10	44	-	CACREF	-	P204	A18	-	AGTIO1	GTIW	GTIOC4B	-	USB_OVRCURB-DS	SCK4	SCK9	SCL0_B	RSPCKB_A	SSIBCK1_A	ET0_RX_DV	-	-	SD0DAT4_A	-	-	TS00	-
D11	53	A9	45	-	-	IRQ2-DS	P203	A19	-	-	-	GTIOC5A	-	CTX0	CTS2_RTS2/SS2	TXD9/MOSI9/SDA9	-	MOSIB_A	-	ET0_COL	-	-	SD0DAT5_A	-	-	TSCAP	-
B12	54	C9	46	-	-	IRQ3-DS	P202	WR1/BC1	-	-	-	GTIOC5B	-	CRX0	SCK2	RXD9/MISO9/SCL9	-	MISOB_A	-	ET0_ERXD2	-	-	SD0DAT6_A	-	-	-	LCD_TCON3_B
A12	55	B9	47	-	-	-	P313	A20	-	-	-	-	-	-	-	-	-	-	-	ET0_ERXD3	-	-	SD0DAT7_A	-	-	-	LCD_TCON2_B
C11	56	-	-	-	-	-	P314	A21	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	ADTRG0	-	-	LCD_TCON1_B
B11	57	-	-	-	-	-	P315	A22	-	-	-	-	-	-	RXD4	-	-	-	-	-	-	-	-	-	-	-	LCD_TCON0_B
A11	58	-	-	-	-	-	P900	A23	-	-	-	-	-	-	TXD4	-	-	-	-	-	-	-	-	-	-	-	LCD_CLK_B
C10	59	-	-	-	-	-	P901	-	-	AGTIO1	-	-	-	-	SCK4	-	-	-	-	-	-	-	-	-	-	-	LCD_DATA15_B
D10	60	D9	48	-	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
D9	61	D8	49	-	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
A10	62	A8	50	33	TRCLK	-	P214	-	-	-	GTIU	-	-	-	-	-	-	QSPCLK	-	ET0_MDC	ET0_MDC	-	SD0CLK_B	-	-	-	LCD_DATA22_B
B10	63	B8	51	34	TRDATA0	-	P211	-	-	-	GTIV	-	-	-	-	-	-	QIO0	-	ET0_MDIO	ET0_MDIO	-	SD0CMD_B	-	-	-	LCD_DATA21_B
A9	64	A7	52	35	TRDATA1	-	P210	-	-	-	GTIW	-	-	-	-	-	-	QIO1	-	ET0_WOL	ET0_WOL	-	SD0CD_B	-	-	-	LCD_DATA20_B
B9	65	B7	53	36	TRDATA2	-	P209	-	-	-	GTOVUP	-	-	-	-	-	-	QIO2	-	ET0_EXOUT	ET0_EXOUT	-	SD0WP_B	-	-	-	LCD_DATA19_B

Note 4. All input pins except for the peripheral function pins already described in the table.
Note 5. P205, P206, P400, P401, P407 to P415, P511, P512, P708 to P713, PB01 (total 22 pins).
Note 6. All input pins except for the ports already described in the table.
Note 7. When VCC is less than 2.7 V, the input voltage of 5V-tolerant ports should be less than 3.6 V, otherwise breakdown may occur because 5V-tolerant ports are electrically controlled so as not to violate the break down voltage.

2.2.3 I/O I_{OH}, I_{OL}

Table 2.5 I/O I_{OH}, I_{OL}

Item			Symbol	Min	Typ	Max	Unit
Permissible output current (average value per pin)	Ports P008 to P010, P201	-	I_{OH}	-	--	–2.0	mA
			I_{OL}	-	-	2.0	mA
	Ports P014, P015	-	I_{OH}	-	-	–4.0	mA
			I_{OL}	-	-	4.0	mA
	Ports P205, P206, P407 to P415, P602, P708 to P713, PB01 (total 19 pins)	Low drive*1	I_{OH}	-	-	–2.0	mA
			I_{OL}	-	-	2.0	mA
		Middle drive*2	I_{OH}	-	-	–4.0	mA
			I_{OL}	-	-	4.0	mA
		High drive*3	I_{OH}	-	-	–20	mA
			I_{OL}	-	-	20	mA
	Other output pins*4	Low drive*1	I_{OH}	-	-	–2.0	mA
			I_{OL}	-	-	2.0	mA
		Middle drive*2	I_{OH}	-	-	–4.0	mA
			I_{OL}	-	-	4.0	mA
		High drive*3	I_{OH}	-	-	–16	mA
			I_{OL}	-	-	16	mA
Permissible output current (max value per pin)	Ports P008 to P010, P201	-	I_{OH}	-	-	–4.0	mA
			I_{OL}	-	-	4.0	mA
	Ports P014, P015	-	I_{OH}	-	-	–8.0	mA
			I_{OL}	-	-	8.0	mA
	Ports P205, P206, P407 to P415, P602, P708 to P713, PB01 (total 19 pins)	Low drive*1	I_{OH}	-	-	–4.0	mA
			I_{OL}	-	-	4.0	mA
		Middle drive*2	I_{OH}	-	-	–8.0	mA
			I_{OL}	-	-	8.0	mA
		High drive*3	I_{OH}	-	-	–40	mA
			I_{OL}	-	-	40	mA
	Other output pins*4	Low drive*1	I_{OH}	-	-	–4.0	mA
			I_{OL}	-	-	4.0	mA
		Middle drive*2	I_{OH}	-	-	–8.0	mA
			I_{OL}	-	-	8.0	mA
		High drive*3	I_{OH}	-	-	–32	mA
			I_{OL}	-	-	32	mA
Permissible output current (max value total pins)	Maximum of all output pins		$\Sigma I_{OH\ (max)}$	-	-	–80	mA
			$\Sigma I_{OL\ (max)}$	-	-	80	mA

Caution: To protect the reliability of the MCU, the output current values should not exceed the values in this table. The average output current indicates the average value of current measured during 100 µs.

Note 1. This is the value when low driving ability is selected in the port drive capability bit in the PmnPFS register. The selected driving ability is retained in Deep Software Standby mode.
Note 2. This is the value when middle driving ability is selected in the port drive capability bit in the PmnPFS register. The selected driving ability is retained in Deep Software Standby mode.
Note 3. This is the value when high driving ability is selected in the port drive capability bit in the PmnPFS register. The selected driving ability is retained in Deep Software Standby mode.

Note 1. FCLK must run at a frequency of at least 4 MHz when programming or erasing the flash memory.
Note 2. See section 9, Clock Generation Circuit in User's Manual for the relationship between the ICLK, PCLKA, PCLKB, PCLKC, PCLKD, FCLK, and BCLK frequencies.
Note 3. When the ADC12 is used, the PCLKC frequency must be at least 1 MHz.

Table 2.11 Operation frequency value in low-speed mode

Item		Symbol	Min	Typ	Max	Unit
Operation frequency	System clock (ICLK)*2	f	-	-	1	MHz
	Peripheral module clock (PCLKA)*2		-	-	1	
	Peripheral module clock (PCLKB)*2		-	-	1	
	Peripheral module clock (PCLKC)*2,*3		-*3	-	1	
	Peripheral module clock (PCLKD)*2		-	-	1	
	Flash interface clock (FCLK)*1, *2		-	-	1	
	External bus clock (BCLK)		-	-	1	
	EBCLK pin output		-	-	1	

Note 1. Programming or erasing the flash memory is disabled in low-speed mode.
Note 2. See section 9, Clock Generation Circuit in User's Manual for the relationship between the ICLK, PCLKA, PCLKB, PCLKC, PCLKD, FCLK, and BCLK frequencies.
Note 3. When the ADC12 is used, the PCLKC frequency must be set to at least 1 MHz.

Table 2.12 Operation frequency value in Subosc-speed mode

Item		Symbol	Min	Typ	Max	Unit
Operation frequency	System clock (ICLK)*2	f	27.8	-	37.7	kHz
	Peripheral module clock (PCLKA)*2		-	-	37.7	
	Peripheral module clock (PCLKB)*2		-	-	37.7	
	Peripheral module clock (PCLKC)*2,*3		-	-	37.7	
	Peripheral module clock (PCLKD)*2		-	-	37.7	
	Flash interface clock (FCLK)*1, *2		27.8	-	37.7	
	External bus clock (BCLK)*2		-	-	37.7	
	EBCLK pin output		-	-	37.7	

Note 1. Programming or erasing the flash memory is disable in Subosc-speed mode.
Note 2. See section 9, Clock Generation Circuit in User's Manual for the relationship between the ICLK, PCLKA, PCLKB, PCLKC, PCLKD, FCLK, and BCLK frequencies.
Note 3. The ADC12 cannot be used.

2.3.2 Clock Timing

Table 2.13 Clock timing except for sub-clock oscillator (1 of 2)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
EBCLK pin output cycle time	t_{Bcyc}	16.6	-	-	ns	Figure 2.3
EBCLK pin output high pulse width	t_{CH}	3.3	-	-	ns	
EBCLK pin output low pulse width	t_{CL}	3.3	-	-	ns	
EBCLK pin output rise time	t_{Cr}	-	-	5.0	ns	
EBCLK pin output fall time	t_{Cf}	-	-	5.0	ns	
SDCLK pin output cycle time	t_{SDcyc}	8.33	-	-	ns	
SDCLK pin output high pulse width	t_{CH}	1.0	-	-	ns	
SDCLK pin output low pulse width	t_{CL}	1.0	-	-	ns	
SDCLK pin output rise time	t_{Cr}	-	-	3.0	ns	
SDCLK pin output fall time	t_{Cf}	-	-	3.0	ns	

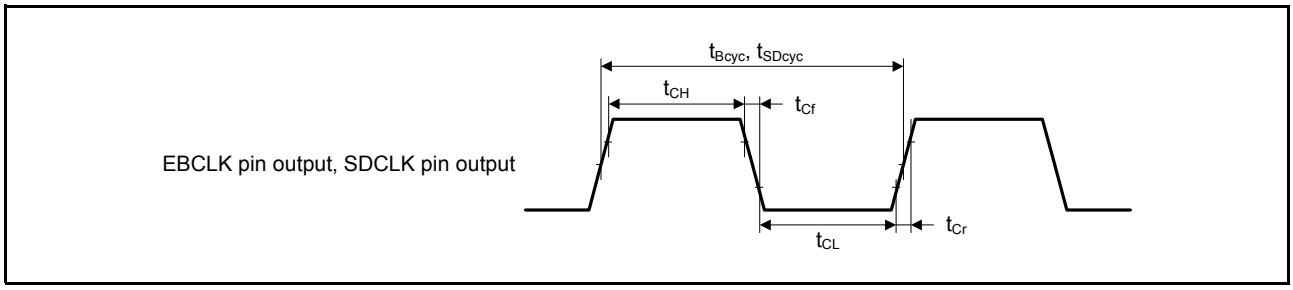


Figure 2.3 EBCLK and SDCLK output timing

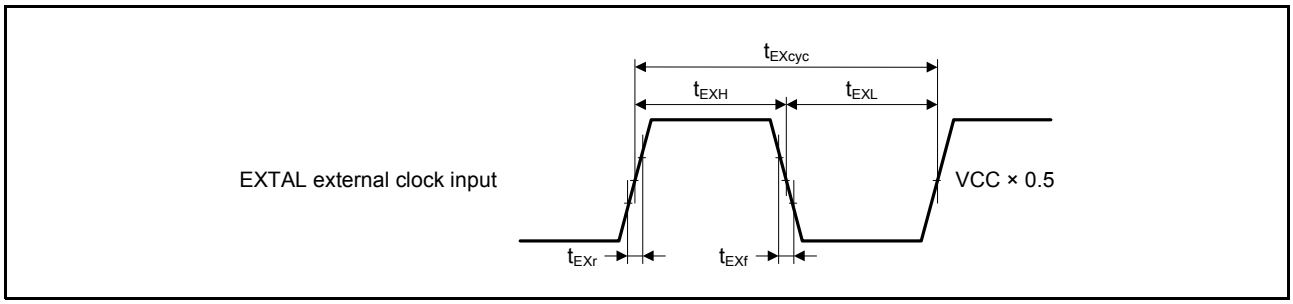


Figure 2.4 EXTAL external clock input timing

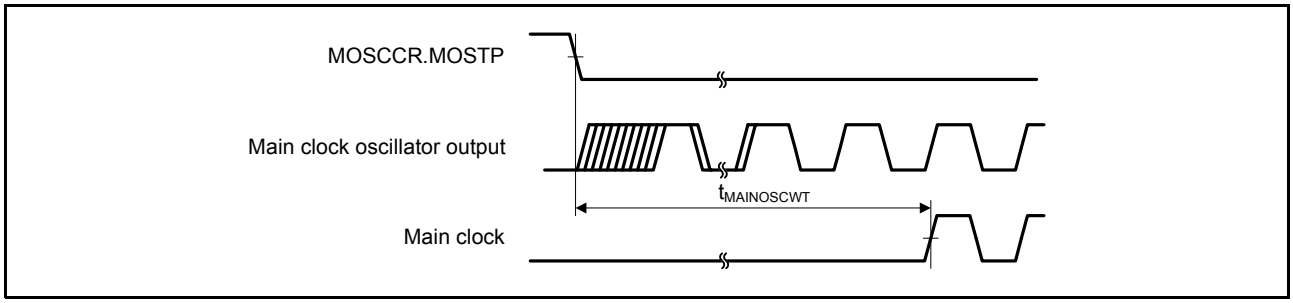


Figure 2.5 Main clock oscillation start timing

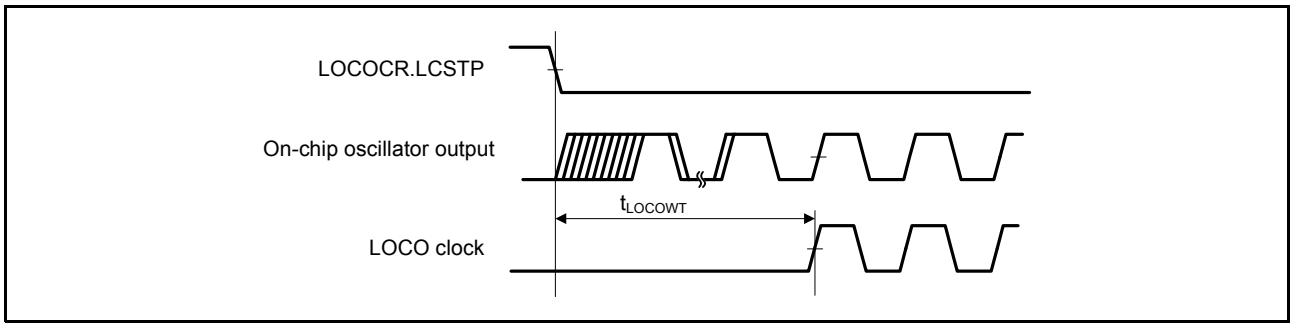
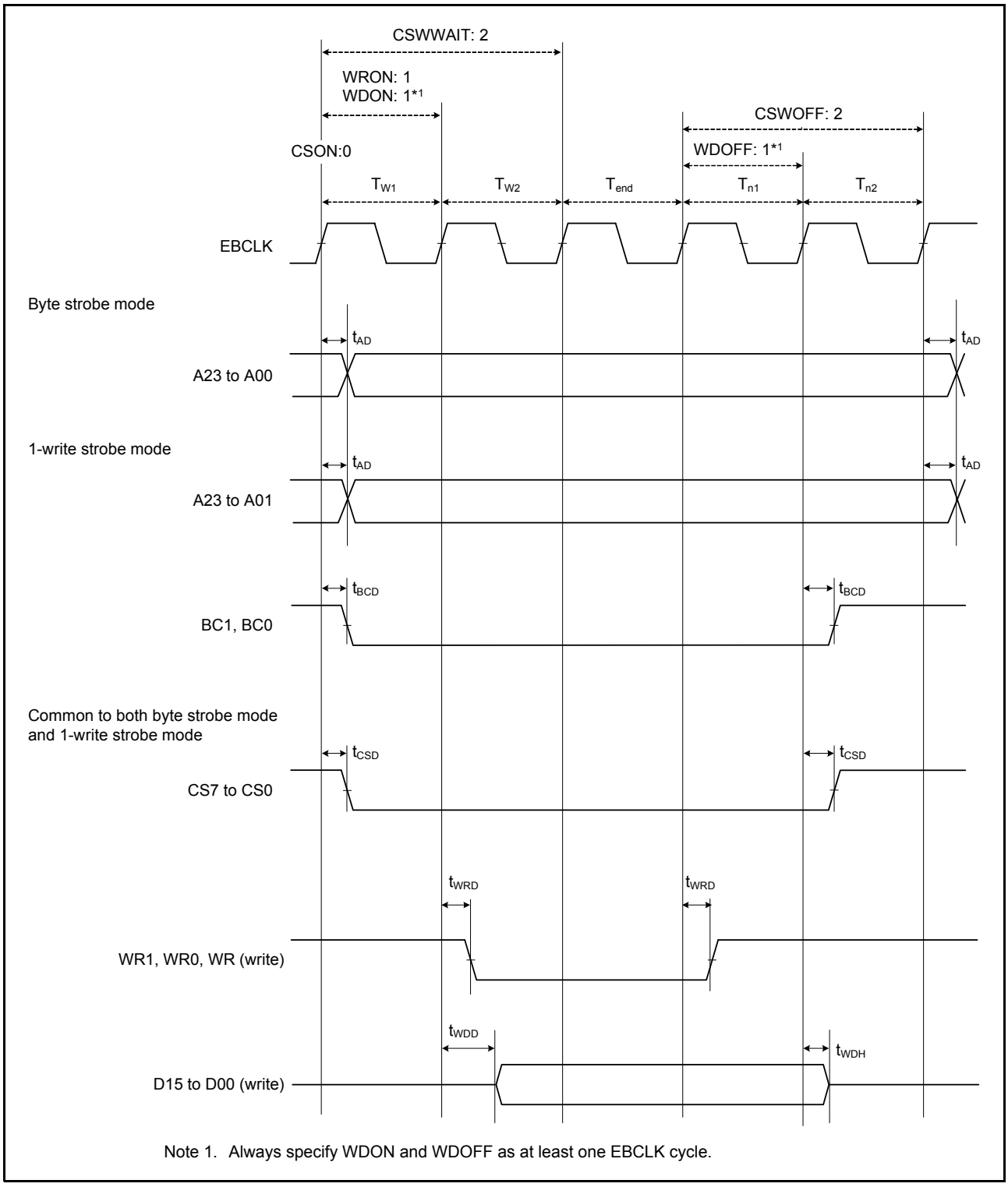


Figure 2.6 LOCO clock oscillation start timing



Note 1. Always specify WDON and WDOFF as at least one EBCLK cycle.

Figure 2.19 External bus timing for normal write cycle with bus clock synchronized

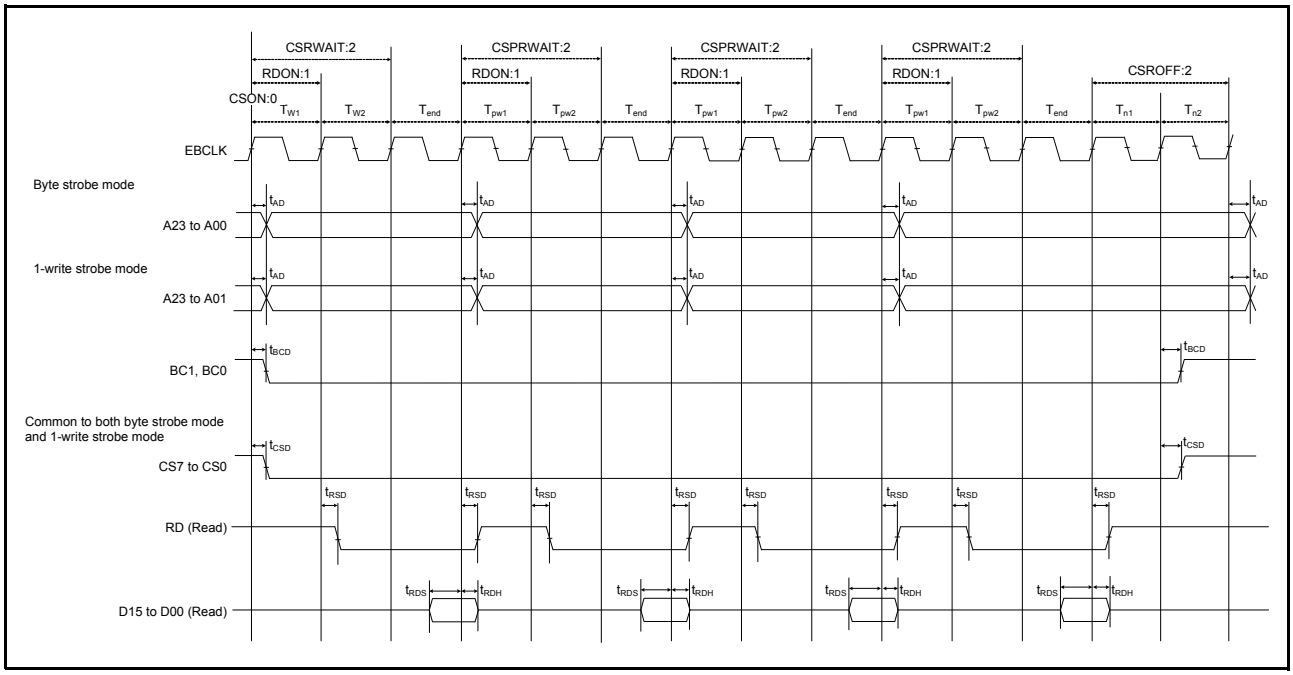
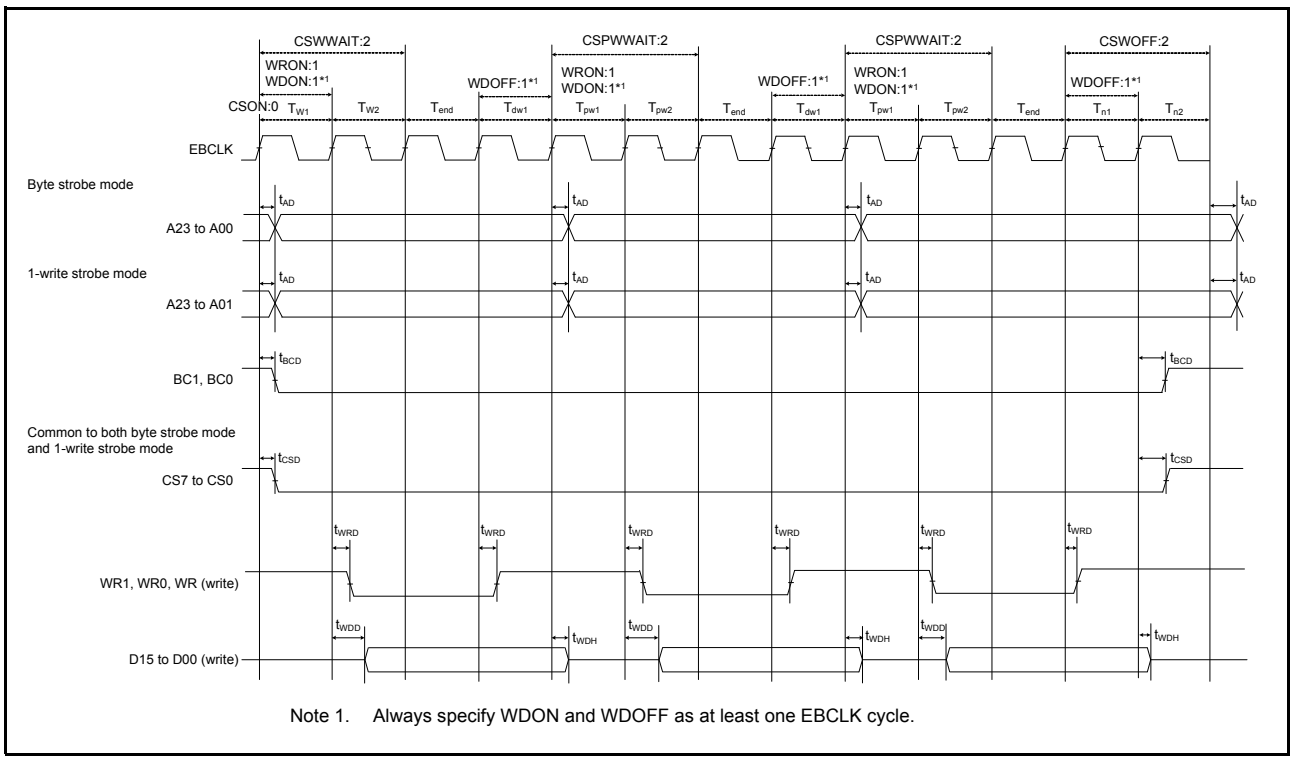
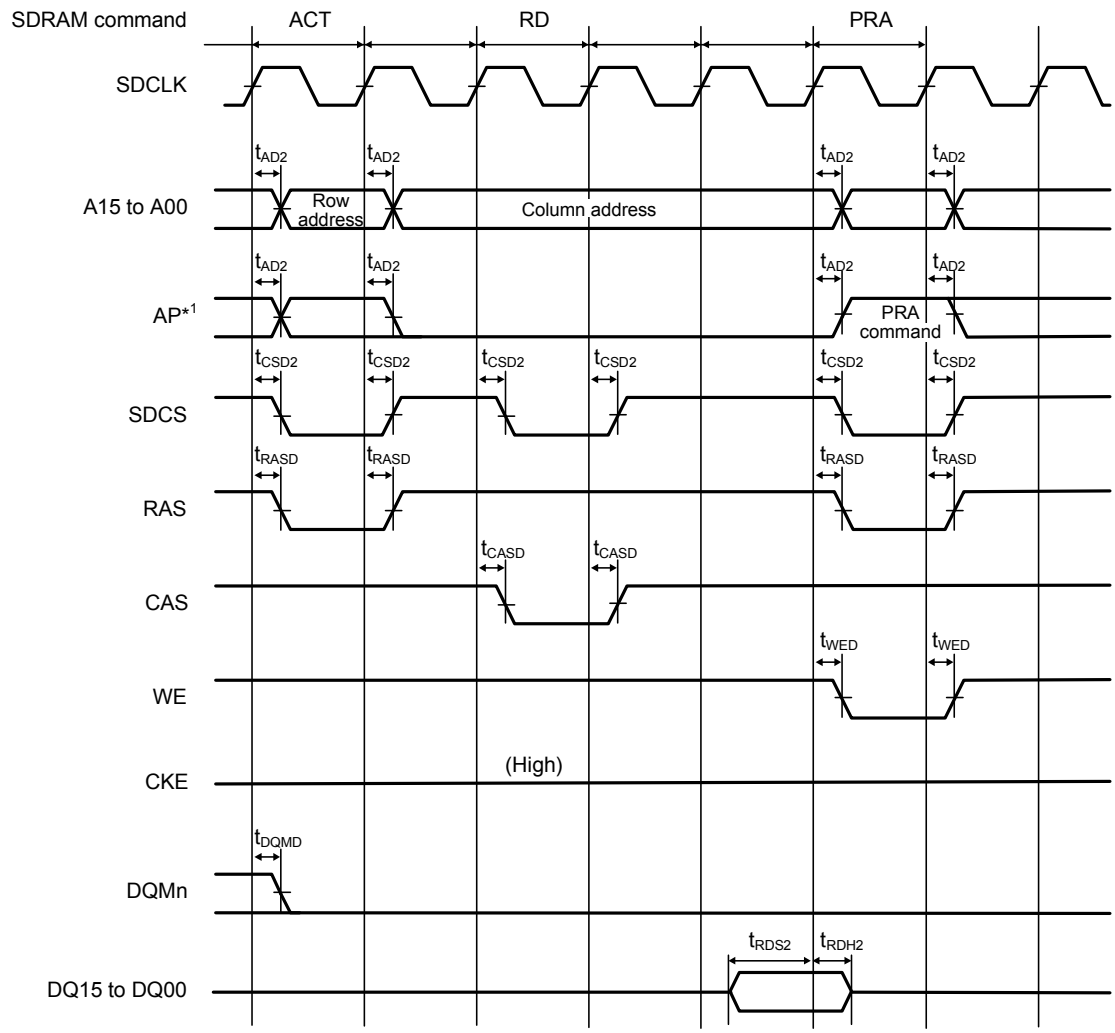


Figure 2.20 External bus timing for page read cycle with bus clock synchronized



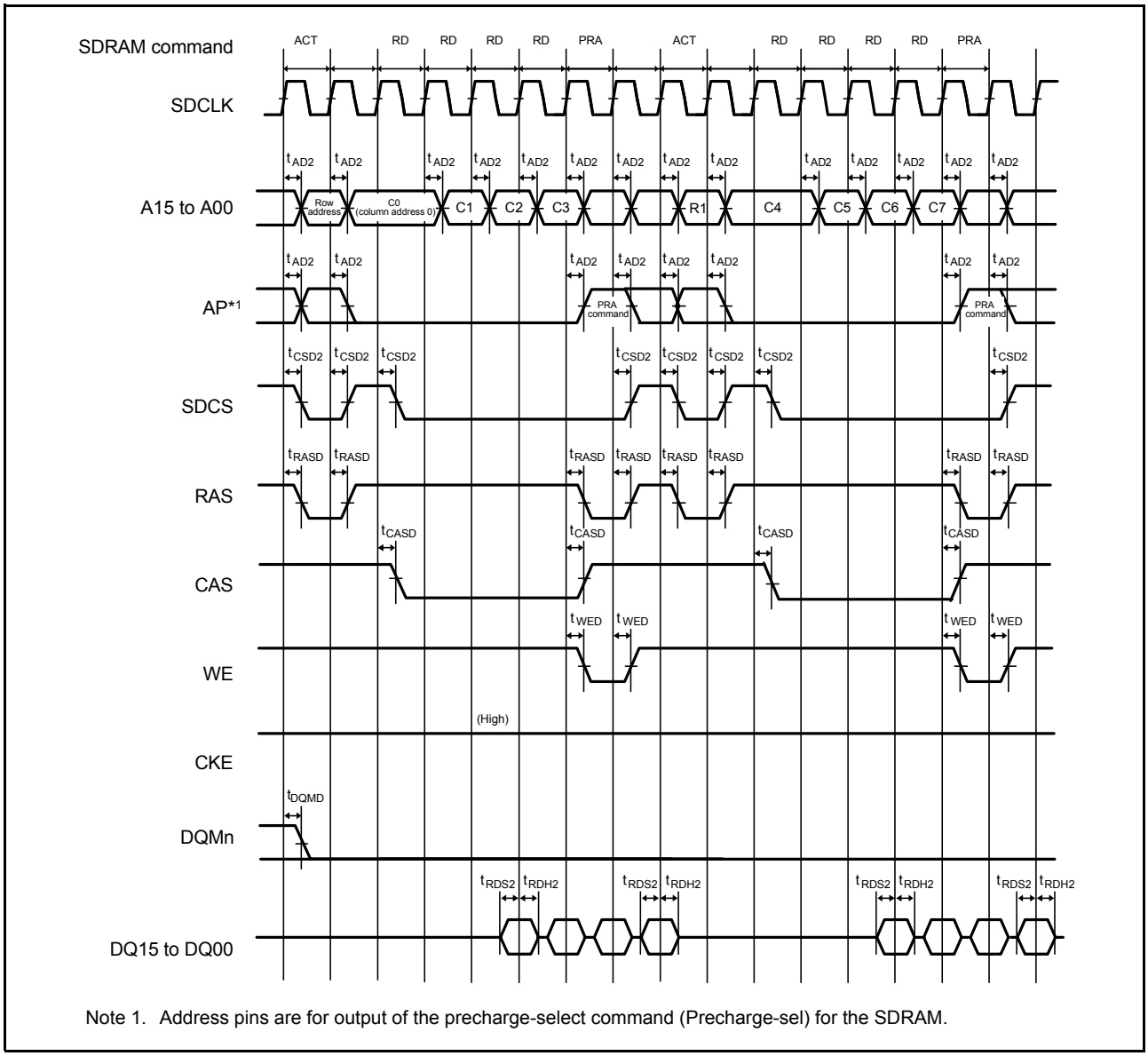
Note 1. Always specify WDON and WDOFF as at least one EBCLK cycle.

Figure 2.21 External bus timing for page write cycle with bus clock synchronized



Note 1. Address pins are for output of the precharge-select command (Precharge-sel) for the SDRAM.

Figure 2.23 SDRAM single read timing



Note 1. Address pins are for output of the precharge-select command (Precharge-sel) for the SDRAM.

Figure 2.27 SDRAM multiple read line stride timing

Note 1. t_{PBcyc}: PCLKB cycle.
Note 2. t_{cac}: CAC count clock source cycle.

2.3.10 SCI Timing

Table 2.22 SCI timing (1)
Conditions: High drive output is selected in the port drive capability bit in the PmnPFS register for the following pins: SCK0 to SCK9.
For other pins, middle drive output is selected in the port drive capability bit in the PmnPFS register.

Item			Symbol	Min	Max	Unit*1	Test conditions
SCI	Input clock cycle	Asynchronous	t_{Scyc}	4	-	t_{Pcyc}	Figure 2.39
		Clock synchronous		6	-		
	Input clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time		t_{SCKr}	-	5	ns	
	Input clock fall time		t_{SCKf}	-	5	ns	
	Output clock cycle	Asynchronous	t_{Scyc}	6	-	t_{Pcyc}	
		Clock synchronous		4	-		
	Output clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time		t_{SCKr}	-	5	ns	
	Output clock fall time		t_{SCKf}	-	5	ns	
	Transmit data delay	Clock synchronous	t_{TXD}	-	25	ns	Figure 2.40
	Receive data setup time	Clock synchronous	t_{RXS}	15	-	ns	
	Receive data hold time	Clock synchronous	t_{RXH}	5	-	ns	

Note 1. t_{Pcyc}: PCLKA cycle.

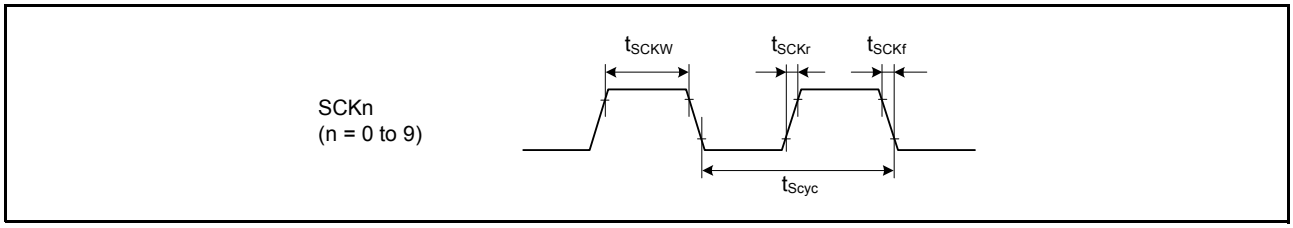


Figure 2.39 SCK clock input/output timing

2.3.11 SPI Timing

Table 2.25 SPI timing
Conditions:
For RSPCKA and RSPCKB pins, high drive output is selected with the port drive capability bit in the PmnPFS register.
For other pins, middle drive output is selected in the port drive capability bit in the PmnPFS register.

Item			Symbol	Min	Max	Unit*1	Test conditions*2
SPI	RSPCK clock cycle	Master	t_{SPcyc}	2 (PCLKA ≤ 60 MHz) 4 (PCLKA > 60 MHz)	4096	t_{Pcyc}	Figure 2.47 C = 30 pF
		Slave		4	4096		
	RSPCK clock high pulse width	Master	t_{SPCKWH}	$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2 - 3$	-	ns	
		Slave		$2 \times t_{Pcyc}$	-		
	RSPCK clock low pulse width	Master	t_{SPCKWL}	$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2 - 3$	-	ns	
		Slave		$2 \times t_{Pcyc}$	-		
	RSPCK clock rise and fall time	Master	t_{SPCKr}, t_{SPCKf}	-	5	ns	
		Slave		-	1	µs	
	Data input setup time	Master	t_{SU}	4	-	ns	Figure 2.48 to Figure 2.53 C = 30 pF
		Slave		5	-		
	Data input hold time	Master (PCLKA division ratio set to 1/2)	t_{HF}	0	-	ns	
		Master (PCLKA division ratio set to a value other than 1/2)	t_H	t_{Pcyc}	-		
		Slave	t_H	20	-		
	SSL setup time	Master	t_{LEAD}	$N \times t_{SPcyc}$ - 10*3	$N \times t_{SPcyc}$ + 100*3	ns	
		Slave		6 x t_{Pcyc}	-	ns	
	SSL hold time	Master	t_{LAG}	$N \times t_{SPcyc}$ - 10 *4	$N \times t_{SPcyc}$ + 100*4	ns	
		Slave		6 x t_{Pcyc}	-	ns	
	Data output delay	Master	t_{OD}	-	6.3	ns	
		Slave		-	20		
	Data output hold time	Master	t_{OH}	0	-	ns	
		Slave		0	-		
	Successive transmission delay	Master	t_{TD}	$t_{SPcyc} + 2 \times t_{Pcyc}$	$8 \times t_{SPcyc} + 2 \times t_{Pcyc}$	ns	
		Slave		$6 \times t_{Pcyc}$			
	MOSI and MISO rise and fall time	Output	t_{Dr}, t_{Df}	-	5	ns	
		Input		-	1	µs	
	SSL rise and fall time	Output	t_{SSLr}, t_{SSLf}	-	5	ns	
		Input		-	1	µs	
	Slave access time		t_{SA}	-	2 x t_{Pcyc} + 28	ns	Figure 2.52 and Figure 2.53 C = 30pF
	Slave output release time		t_{REL}	-	2 x t_{Pcyc} + 28		

Note 1. t_{Pcyc}: PCLKA cycle.

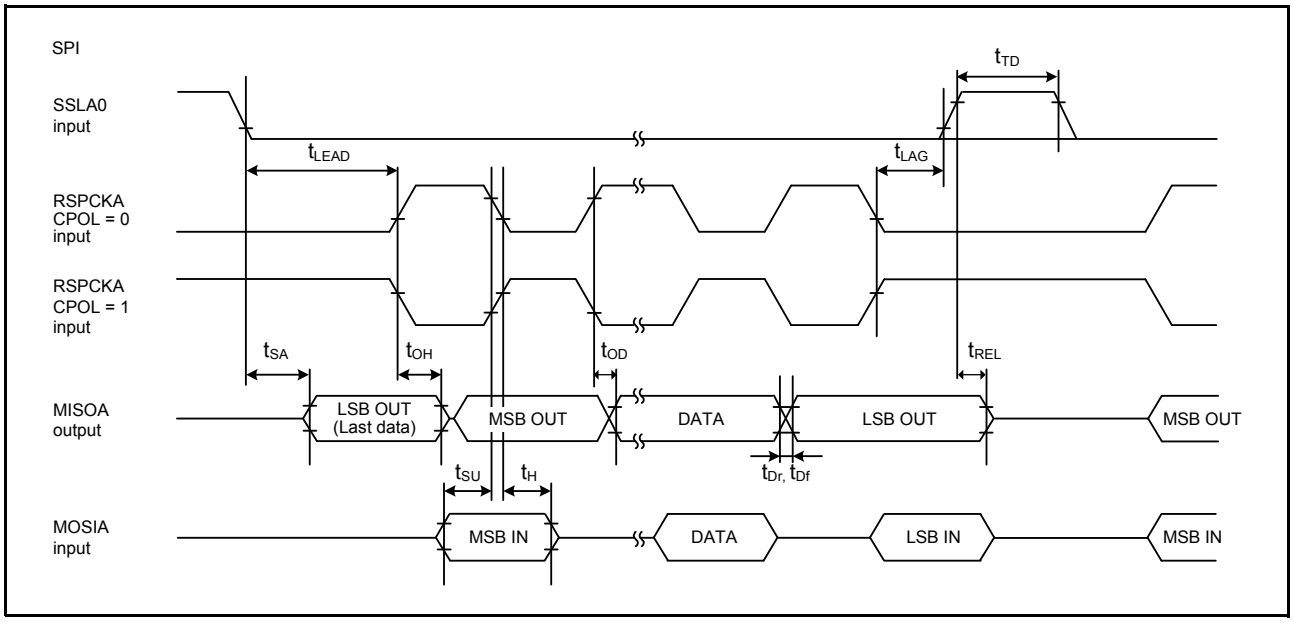


Figure 2.53 SPI timing for slave when CPHA = 1

2.3.12 QSPI Timing

Table 2.26 QSPI timing
Conditions: High drive output is selected in the port drive capability bit in the PmnPFS register.

Item		Symbol	Min	Max	Unit*1	Test conditions
QSPI	QSPCK clock cycle	t_{QScyc}	2	48	t_{Pcyc}	Figure 2.54
	QSPCK clock high pulse width	t_{QSWH}	t_{QScyc} × 0.4	-	ns	
	QSPCK clock low pulse width	t_{QSWL}	t_{QScyc} × 0.4	-	ns	
	Data input setup time	t_{Su}	8	-	ns	Figure 2.55
	Data input hold time	t_{IH}	0	-	ns	
	QSSL setup time	t_{LEAD}	(N+0.5) x t_{Qscyc} - 5 *2	(N+0.5) x t_{Qscyc} +100 *2	ns	
	QSSL hold time	t_{LAG}	(N+0.5) x t_{Qscyc} - 5 *3	(N+0.5) x t_{Qscyc} +100 *3	ns	
	Data output delay	t_{OD}	-	4	ns	
	Data output hold time	t_{OH}	–3.3	-	ns	
	Successive transmission delay	t_{TD}	1	16	t_{QScyc}	

Note 1. t_{Pcyc}: PCLKA cycle.
Note 2. N is set to 0 or 1 in SFMSLD.
Note 3. N is set to 0 or 1 in SFMSHD.

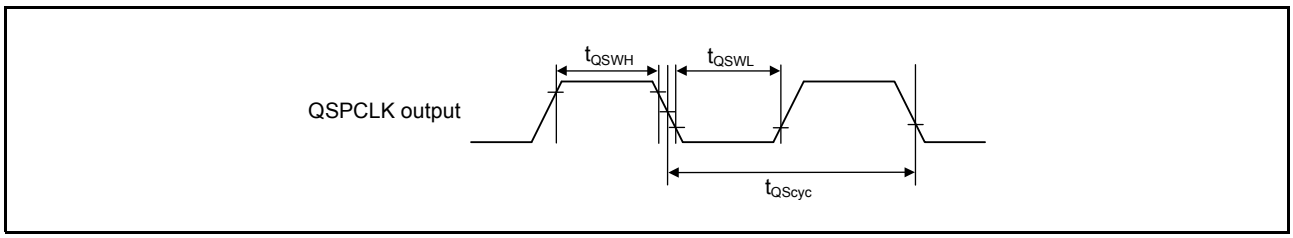


Figure 2.54 QSPI clock timing

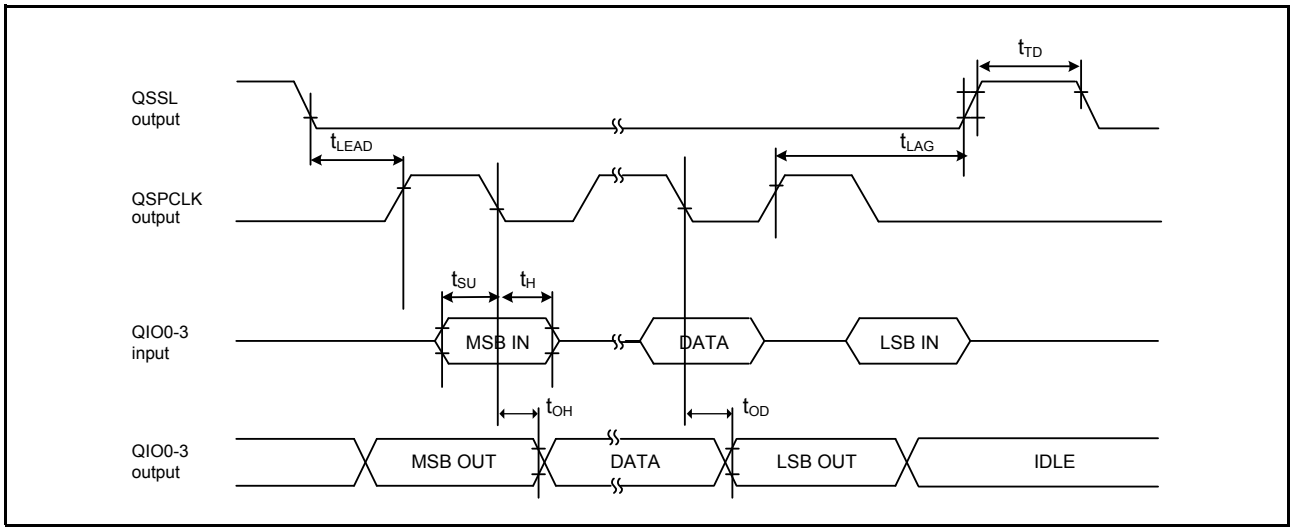


Figure 2.55 Transmit and receive timing

2.3.13 IIC Timing

Table 2.27 IIC timing (1) (1 of 2)

(1) Conditions: Middle drive output is selected in the port drive capability bit in the PmnPFS register for the following pins: SDA0_B, SCL0_B, SDA1_A, SCL1_A, SDA1_B, SCL1_B.

(2) The following pins do not require setting: SCL0_A, SDA0_A, SCL2, SDA2.

(3) Use pins that have a letter appended to their names, for instance "_A" or "_B", to indicate group membership. For the IIC interface, the AC portion of the electrical characteristics is measured for each group.

Item		Symbol	Min*1	Max	Unit	Test conditions*3
IIC (Standard mode, SMBus) ICFER.FMPE = 0	SCL input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 1300	-	ns	Figure 2.56
	SCL input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL, SDA input rise time	t_{Sr}	-	1000	ns	
	SCL, SDA input fall time	t_{Sf}	-	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA input bus free time when wakeup function is disabled	t_{BUF}	3 (6) × t_{IICcyc} + 300	-	ns	
	SDA input bus free time when wakeup function is enabled	t_{BUF}	3 (6) × t_{IICcyc} + 4 × t_{Pcyc} + 300	-	ns	
	START condition input hold time when wakeup function is disabled	t_{STAH}	t_{IICcyc} + 300	-	ns	
	START condition input hold time when wakeup function is enabled	t_{STAH}	1 (5) × t_{IICcyc} + t_{Pcyc} + 300	-	ns	
	Repeated START condition input setup time	t_{STAS}	1000	-	ns	
	STOP condition input setup time	t_{STOS}	1000	-	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	

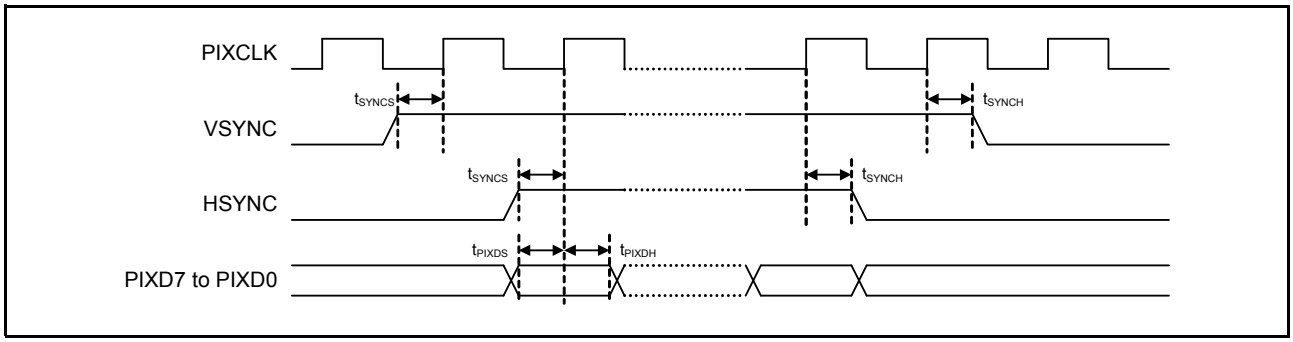


Figure 2.75 PDC AC timing

2.3.18 GLCDC Timing

Table 2.33 GLCDC timing
Conditions:
LCD_CLK: High drive output is selected in the port drive capability bit in the PmnPFS register.
LCD_DATA: Middle drive output is selected in the port drive capability bit in the PmnPFS register.

Item		Symbol	Min	Typ	Max	Unit	Test conditions
LCD_EXTCLK input clock frequency		t_{Ecyc}	-	-	60*1	MHz	Figure 2.76
LCD_EXTCLK input clock low pulse width		t_{WL}	0.45	-	0.55	t_{Ecyc}	
LCD_EXTCLK input clock high pulse width		t_{WH}	0.45	-	0.55		
LCD_CLK output clock frequency		t_{Lcyc}	-	-	60*1	MHz	Figure 2.77
LCD_CLK output clock low pulse width		t_{LOL}	0.4	-	0.6	t_{Lcyc}	Figure 2.77
LCD_CLK output clock high pulse width		t_{LOH}	0.4	-	0.6	t_{Lcyc}	Figure 2.77
LCD data output delay timing	_A or _B combinations*2	t_{DD}	–3.5	-	4	ns	Figure 2.78
	_A and _B combinations*3		–5.0	-	5.5		

Note 1. Parallel RGB888, 666,565: Maximum 54 MHz
Serial RGB888: Maximum 60 MHz (4x speed)
Note 2. Use pins that have a letter appended to their names, for instance, “_A” or “_B”, to indicate
Note 3. Pins of group “_A” and “_B” combinations are used.

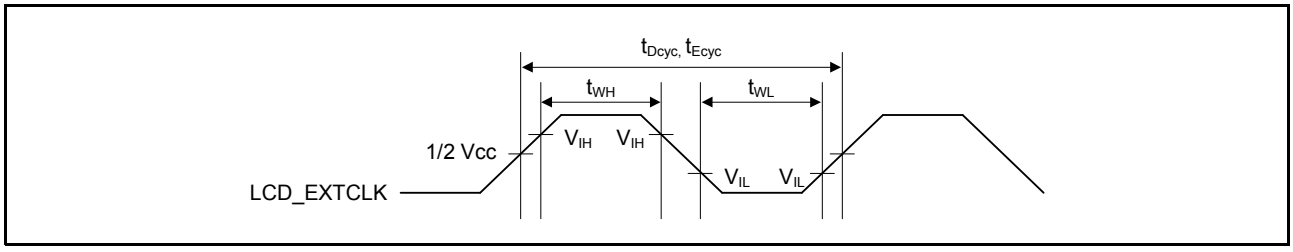


Figure 2.76 LCD_EXTCLK clock input timing

Table 2.41 A/D conversion characteristics for unit 1 (2 of 2)
Conditions: PCLKC = 1 to 60 MHz

Item			Min	Typ	Max	Unit	Test conditions
Channel-dedicated sample-and-hold circuits not in use (AN100 to AN102)	Conversion time*1 (Operation at PCLKC = 60 MHz)	Permissible signal source impedance Max. = 1 kΩ	0.48 (0.267)*2	-	-	µs	Sampling in 16 states
	Offset error		-	±1.0	±2.5	LSB	-
	Full-scale error		-	±1.0	±2.5	LSB	-
	Absolute accuracy		-	±2.0	±4.5	LSB	-
	DNL differential nonlinearity error		-	±0.5	±1.5	LSB	-
	INL integral nonlinearity error		-	±1.0	±2.5	LSB	-
High-precision channels (AN103, AN105 to AN107)	Conversion time*1 (Operation at PCLKC = 60 MHz)	Permissible signal source impedance Max. = 1 kΩ	0.48 (0.267)*2	-	-	µs	Sampling in 16 states
		Max. = 400 Ω	0.40 (0.183)*2	-	-	µs	Sampling in 11 states VCC = AVCC0 = 3.0 to 3.6 V 3.0 V ≤ VREFH ≤ AVCC0
	Offset error		-	±1.0	±2.5	LSB	-
	Full-scale error		-	±1.0	±2.5	LSB	-
	Absolute accuracy		-	±2.0	±4.5	LSB	-
	DNL differential nonlinearity error		-	±0.5	±1.5	LSB	-
	INL integral nonlinearity error		-	±1.0	±2.5	LSB	-
Normal-precision channels (AN116 to AN119)	Conversion time*1 (Operation at PCLKC = 60 MHz)	Permissible signal source impedance Max. = 1 kΩ	0.88 (0.667)*2	-	-	µs	Sampling in 40 states
	Offset error		-	±1.0	±5.5	LSB	-
	Full-scale error		-	±1.0	±5.5	LSB	-
	Absolute accuracy		-	±2.0	±7.5	LSB	-
	DNL differential nonlinearity error		-	±0.5	±4.5	LSB	-
	INL integral nonlinearity error		-	±1.0	±5.5	LSB	-

Note: These specification values apply when there is no access to the external bus during A/D conversion. If access occurs during A/D conversion, values might not fall within the indicated ranges.
The use of pins AN100 to AN103, AN105 to AN107 as digital outputs is not allowed when the 12-Bit A/D converter is used.
The characteristics apply when AVCC0, AVSS0, VREFH0/VREFH, VREFL0, VREFL, and 12-bit A/D converter input voltage is stable.
Note 1. The conversion time includes the sampling and comparison times. The number of sampling states is indicated for the test conditions.
Note 2. Values in parentheses indicate the sampling time.

Table 2.42 A/D conversion characteristics for simultaneous using of channel-dedicated sample-and-hold circuits in unit0 and unit1
Conditions: PCLKC = 30/60 MHz

Item		Min	Typ	Max	Test conditions
Channel-dedicated sample-and-hold circuits in use with continious sampling function enabled (AN000 to AN002)	Offset error	-	±1.5	±5.0	• PCLKC = 60 MHz • Sampling in 15 states
	Full-scale error	-	±2.5	±5.0	
	Absolute accuracy	-	±4.0	±8.0	
Channel-dedicated sample-and-hold circuits in use with continious sampling function enabled (AN100 to AN102)	Offset error	-	±1.5	±5.0	
	Full-scale error	-	±2.5	±5.0	
	Absolute accuracy	-	±4.0	±8.0	
Channel-dedicated sample-and-hold circuits in use with continious sampling function enabled (AN000 to AN002)	Offset error	-	±1.5	±3.5	• PCLKC = 30 MHz • Sampling in 7 states
	Full-scale error	-	±1.5	±3.5	
	Absolute accuracy	-	±3.0	±5.5	
Channel-dedicated sample-and-hold circuits in use with continious sampling function enabled (AN100 to AN102)	Offset error	-	±1.5	±3.5	
	Full-scale error	-	±1.5	±3.5	
	Absolute accuracy	-	±3.0	±5.5	

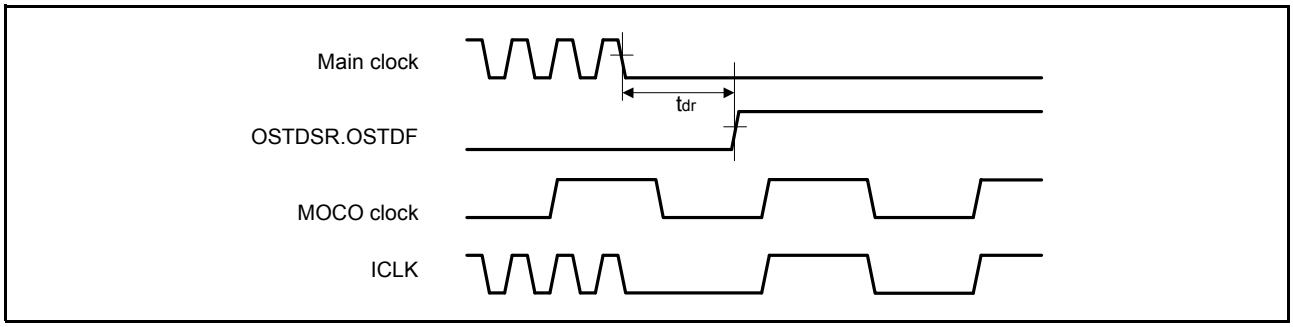


Figure 2.92 Oscillation stop detection timing

2.9 POR and LVD Characteristics

Table 2.47 Power-on reset circuit and voltage detection circuit characteristics

Item			Symbol	Min	Typ	Max	Unit	Test conditions
Voltage detection level	Power-on reset (POR)	Module-stop function disabled*2	V_{POR}	2.5	2.6	2.7	V	Figure 2.93
		Module-stop function enabled*3		1.8	2.25	2.7		
	Voltage detection circuit (LVD0)		V_{det0_1}	2.84	2.94	3.04		Figure 2.94
			V_{det0_2}	2.77	2.87	2.97		
			V_{det0_3}	2.70	2.80	2.90		
	Voltage detection circuit (LVD1)		V_{det1_1}	2.89	2.99	3.09		Figure 2.95
			V_{det1_2}	2.82	2.92	3.02		
			V_{det1_3}	2.75	2.85	2.95		
	Voltage detection circuit (LVD2)		V_{det2_1}	2.89	2.99	3.09		Figure 2.96
			V_{det2_2}	2.82	2.92	3.02		
			V_{det2_3}	2.75	2.85	2.95		
Internal reset time	Power-on reset time		t_{POR}	-	4.5	-	ms	Figure 2.93
	LVD0 reset time		t_{LVD0}	-	0.51	-		Figure 2.94
	LVD1 reset time		t_{LVD1}	-	0.38	-		Figure 2.95
	LVD2 reset time		t_{LVD2}	-	0.38	-		Figure 2.96
Minimum VCC down time*1			t_{VOFF}	200	-	-	µs	Figure 2.93, Figure 2.94
Response delay			t_{det}	-	-	200	µs	Figure 2.93 to Figure 2.96
LVD operation stabilization time (after LVD is enabled)			$t_{d(E-A)}$	-	-	10	µs	Figure 2.95, Figure 2.96
Hysteresis width (LVD1 and LVD2)			V_{LVH}	-	70	-	mV	

Note 1. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det1}, and V_{det2} for POR and LVD.
Note 2. The low-power function is disabled and DEEPCUT[1:0] = 00b or 01b.
Note 3. The low-power function is enabled and DEEPCUT[1:0] = 11b.

2.17 Serial Wire Debug (SWD)

Table 2.57 SWD

Item	Symbol	Min	Typ	Max	Unit	Test conditions
SWCLK clock cycle time	$t_{SWCKcyc}$	40	-	-	ns	Figure 2.104
SWCLK clock high pulse width	t_{SWCKH}	15	-	-	ns	
SWCLK clock low pulse width	t_{SWCKL}	15	-	-	ns	
SWCLK clock rise time	t_{SWCKr}	-	-	5	ns	
SWCLK clock fall time	t_{SWCKf}	-	-	5	ns	
SWDIO setup time	t_{SWDS}	8	-	-	ns	Figure 2.105
SWDIO hold time	t_{SWDH}	8	-	-	ns	
SWDIO data delay time	t_{SWDD}	2	-	28	ns	

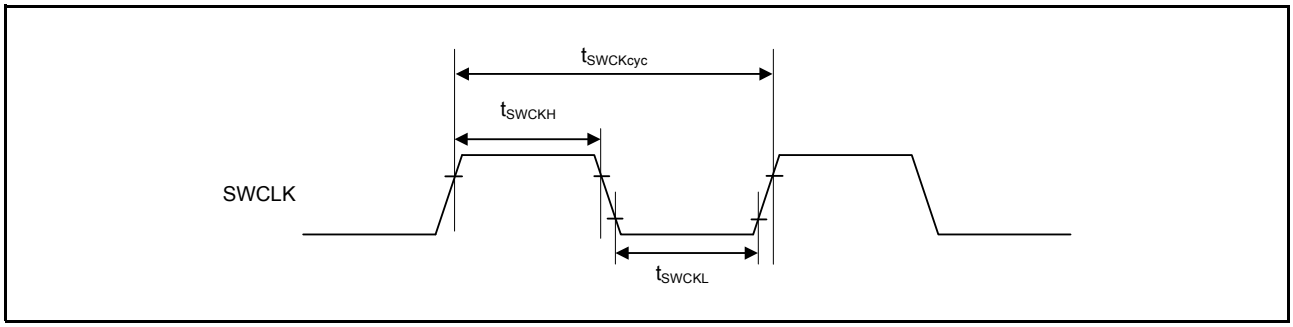
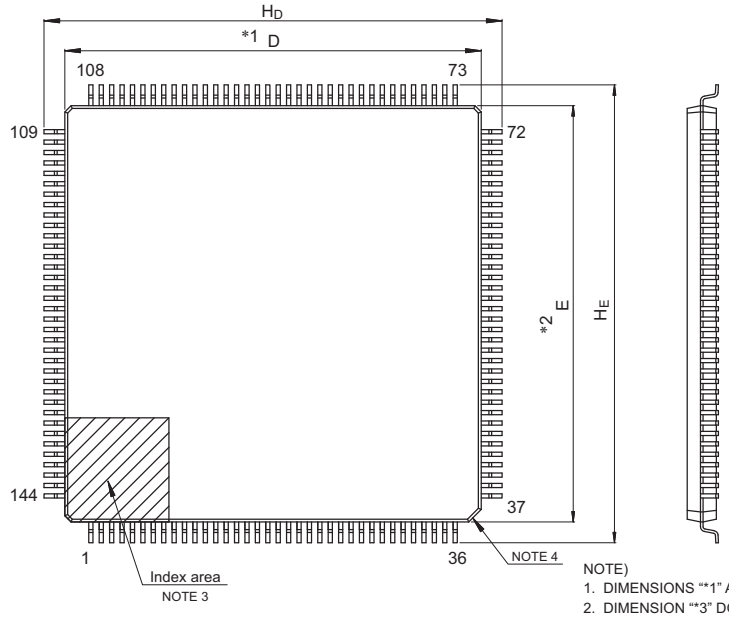
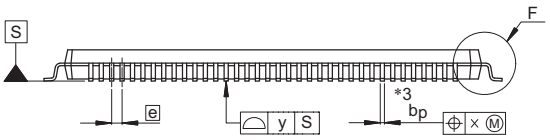


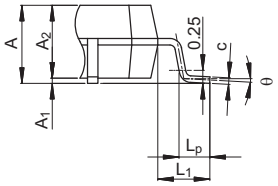
Figure 2.104 SWD SWCLK timing

JEITA Package Code	RENESAS Code	Previous Code	MASS (Typ) [g]
P-LFQFP144-20x20-0.50	PLQP0144KA-B	—	1.2

Unit: mm







Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.
3. PIN 1 VISUAL INDEX FEATURE MAY VARY, BUT MUST BE LOCATED WITHIN THE HATCHED AREA.
4. CHAMFERS AT CORNERS ARE OPTIONAL, SIZE MAY VARY.

Reference Symbol	Dimensions in millimeters		
	Min	Nom	Max
D	19.9	20.0	20.1
E	19.9	20.0	20.1
A_2	—	1.4	—
H_D	21.8	22.0	22.2
H_E	21.8	22.0	22.2
A	—	—	1.7
A_1	0.05	—	0.15
b_p	0.17	0.20	0.27
c	0.09	—	0.20
θ	0°	3.5°	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
L_p	0.45	0.6	0.75
L_1	—	1.0	—

Figure 1.4 144-pin LQFP

Revision History	S5D9 Microcontroller Datasheet

Rev.	Date	Chapter	Summary
1.00	Nov 3, 2016	—	First Edition issued

S5D9 Microcontroller Datasheet

Publication Date: Rev. 1.00 Nov 3, 2016

Published by: Renesas Electronics Corporation